



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SC-75A					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	120	60 000	200 °C + N2	0	0
HAST	378	37 800	130 °C, 85 % RH	0	0
Pressure Pot	446	42 816	121°, 15 PSIG	0	0
Solder DUNK	95	285	260 °C, 10 s	0	0
Solderability	45	210	883 M2003	0	0
Temp. Cycle	1146	712 724	-55 °C to 150 °C	0	0